



NOTES:  
 1) R8, R9 and R19 are for test purposes.  
 2) Built on PMP3114 Rev\_A PCB  
 3) Ref. des. > 99 were added

Transformer T1:  
 Core: EFD20 Epcos, N87, half core ungapped + 0.25mm gapped, Al=160  
 Primary winding: 3 x 45x0.1 Litz wire in parallel, 4 turns  
 Secondary winding: 12 turns 45x0.1 Litz wire  
 Isolation: 2 layers mylar 0.05mm  
 Wind first the primary then the secondary  
 Ungapped core p/n: B66417G0000X187  
 0.25mm gapped core p/n: B66417U0160K187



Title			2.7V...5.5V to 12V@1A		
Size	Number	Rev			
B	PMP7034	A			
Date	10/11/2011	Drawn by	<Name>		
Filename	PMP7034 Rev_A_pads.sch	Sheet	1 of 1		
Engineer	<Engineer>				10/11/2011

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